	02	-07-	200	0	E	INTS O	NLY							
						530 F New 1	ifth Ave	lew York		id, p	.C.			
MRI	D 10	.6.	95			Attorn	ley Doo	cket Nu. A	50108-	<u>3133</u>				
Applic				MURA	Makoto	o and F	UJINA	Mi Yasusi	ni ·					
For		;	DATA MEDIL		DUCT	ION AF	PARAT	rus and	DATA	stof	RAGE			
Intern Filing	ational A Date	pplicat :	ion Decen	iber 19	i, 1991									
	issioner of Igion, U.C.		and Trad	emarks										
1.	Names	of Conve	ying Part	65		:	KAWA	MURA Mak	oto and i	FUJIN	AMI Ya	isushi		
2.	Name a	nd addre	55 OI 190	elving pi	arty	;	7-35,	Corporation Kitoshinagay gawa-ku, To	va 6-choi					
З.	Nature d Executio	of Convey on Date	yance	: ;	<u>Assign</u> Septer	ment. nber 18	<u>1995</u> .	0	8/49	155	06			
4.	<b>1</b> 7	Thia do	ion No. ( cument is ion is:	s being f	filed toge	:T/JP94/ athor with	02133 (נ a חפא a	USSN 08/49 application, t	5,506) he cxecu	ilion d	ate of I	ihe		
δ.		nd addre ument st			ion the l	recorded	assignm	ont and any	corresp	onden	ice con	ະອຸດາທິດຮູ	3	
		William S. Fromme			mer			NEWA	DDO.E	223	Ĥ S	OF .	111:	7 97
		e	CURTIS	h-Aveniu	IS & EA	FFORD, 2036.	P.C.	FROM 145 NEW	FIFT	ТН	AVC		-	
6.	Total n	າບາກການອາ ດໃ	applicati	ons and	patents	involved:	1.							
7.	Total Fr N	36 (37 Cl Fee on	FH 3.41): closed, C			·		•						
8.	0 6	If any a		fee la re	quired, a			uplicale copy o Iroby given t			<b>g</b> by dep	iosit and	sunl),	
9.	To the	ent and S Dest of n a true c	ny knowl	edgo and			ning info	ormation is t	rue and g	orraci	t and a	ny alta	ched	-

Will William S. Frommer, Esg. Name of Person Signing Signature / OCTOBER 6, 1995 Dale

1 Aucr

> PATENT REEL: 010365 FRAME: 0673

P. 03

Docket Number: 450108.3133

## ASSIGNMENT

WHERPAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below)of certain new and useful improvements in

## DATA REPRODUCTION APPARATUS AND DATA STORAGE MEDIUM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WILEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORU, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIONEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries forcign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents to issue the said United States I etters Patent to said ASSIGNEE, as the assignee of the whole right, title and Interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect the in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of sold application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, cale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sule.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 08/495,306\_\_\_\_\_\_, Filing Date; \_\_\_\_\_\_

This assignment executed on the dates indicated below.

MAKOTO KAWAMURA

Name of first or sole inventor

18	September	- 199

Execution date of U.S. Patent Application

Date of this assignment

Kanagawa, Japan

Residence of first or sole inventor

makoto Kawamura

Signature of first or sole inventor

YASUSHI FUJINAMI

Name of second inventor

18 September (9" Execution date of U.S. Patent Application

Konagawa, Japan

Residence of second inventor

Jose 5 5 Fylenemi

18 September

Dute of this sector

PATENT REEL: 010365 FRAME: 0674

**RECORDED: 10/06/1995**